

IPC ERFA-møde, torsdag den 22. november 2018

Afholdes hos HYTEK, Sofievej 61, 9000 Aalborg

Dagsorden:

- 10:00** **Velkomst** v/Alex Christensen, HYTEK
- 10:05** **Nyt fra IPC** v/Alex Christensen, HYTEK
- Gennemgang af de nyeste udgivne IPC-standarder
- 10:15** **Klipning, fræsning, laserskæring** v/ Arne Fast, EP-TeQ A/S
- Lasertyper
 - Fordele og ulemper ved laserskæring
- Indstøbning** v/ Arne Fast, EP-TeQ A/S
- Hvorfor lave indstøbning?
 - Materialetyper
 - Vacuum
- 11:15** **Hitliste** v/ Kim Ankeråa, HYTEK
- Top 5 inden for fejl på PCB
 - Top 5 inden for fejl på assembly
 - Hvad er årsagen til disse fejltyper?
 - Hvordan kan man undgå dem?
- 12:15** **Frokost / lunch**
- 13.15** **Surface analytics and Quicktests** v/Dr. Olaf Schoenfeld and Thomas Møller, Zestron
- How clean is clean? When manufacturing electronic assemblies, impurities left on the board's surface or underneath the components may lead to in-field failures. This lecture provides an overview of methodologies available to properly assess the cleanliness of your assemblies following the cleaning process
 - **Topics include:**
 - Surface analysis for cleanliness assessment
 - Measurement of standards demands
 - Use of analysis processes in the production line
 - Handling of analysis tools for quality control of supplied components
- 14:15** **Eventuelt**